

ABSTRACT OF THE DISCLOSURE

A method of manipulating preferable thin wafers, preferably having a thickness of less than 200 μm , wherein the wafers are placed prior to polishing or another processing step for reducing the thickness thereof on a transportable electrostatic carrier. The wafers remain on the transportable electrostatic carrier for the duration of and between at least two processing steps, during the manipulating steps and during any necessary intermediate storage.

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